COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

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the specification of wh	nich				
X is attached herei was filed on as Application S		d was amended on	•		
specification, including I acknowledge t application in accorda I hereby claim foreign application(s)	g the claims, as amend he duty to disclose into ince with Title 37, Code foreign priority benefit for patent or inventors on for patent or inventority is claimed:	and understood the conterded by any amendment refer formation which is material to e of Federal Regulations, § ts under Title 35, United Socrtificate listed below and tor's certificate having a filing	red to above. to the patentat 1.56(a). tates Code, § have also ide	oility of this 119 of any ntified below	
Number	Country	Date Filed(yyyy/mm/dd)	Yes	No	
92118568	Taiwan, R.O.C.	2003/7/8	×		
		•		ation and to	
SEND CORRESPONDENCE TO:			DIRECT TELEPHONE CALLS TO: (Name and Telephone Number)		

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: Humg Min-Lung Date: 6/88/04

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